## OUTLINES DIMENSIONS



Notes:

1. All Dimensions are in millimeters (inches).
2. Tolerance is $\pm 0.25 \mathrm{~mm}$ ( $0.01^{\prime \prime}$ ) unless otherwise noted.

3 . Specifications are subject to change without notice.

| Part Number | Chip Material | Color of Emission | Lens Type | Description |
| :---: | :---: | :---: | :---: | :---: |
| CTD3939B2WB | InGaN | Blue | White | Touch Display |


| Parameter | Symbol | Max Rating | Unit |
| :--- | :---: | :---: | :---: |
| Power Dissipation | PD | 120 | mW |
| Continuous Forward Current (Per Dice) | IF | 30 | mA |
| Peak Current (Per Dice) | IFP | 100 | mA |
| Reverse Voltage (Per Dice) | VR | 5 | V |
| Operating Temperature Range | ToPR | $-25 \sim+85$ | ${ }^{\circ} \mathrm{C}$ |
| Storage Temperature Range | TsTG | $-25 \sim+85$ | ${ }^{\circ} \mathrm{C}$ |
| Hand Soldering Condition: $360^{\circ} \mathrm{C} / 3 \mathrm{sec}$ |  |  |  |

OPTICAL-ELECTRICAL CHARACTERISTICS
(TA $=25^{\circ} \mathrm{C}$ )

| Parameter | Symbol | Test Condition | Value |  |  |  |
| :--- | :---: | :---: | :---: | :---: | :---: | :---: |
|  |  |  | Min | Typ | Max |  |
| Luminous Intensity | $I_{V}$ |  | - | 60 | - | mcd |
| Forward Voltage | $\mathrm{VF}_{\mathrm{F}}$ | $\mathrm{I}_{\mathrm{F}}=20 \mathrm{~mA}$ | - | 3.2 | 4.0 | V |
| Reverse Leakage Current | $\mathrm{I}_{\mathrm{R}}$ | $\mathrm{V}_{\mathrm{R}}=5 \mathrm{~V}$ | - | - | 10 | $\mu \mathrm{~A}$ |
| Dominant Wavelength | $\lambda_{\mathrm{D}}$ | $\mathrm{I}_{\mathrm{F}}=20 \mathrm{~mA}$ | 460 | 470 | 475 | nm |
| Spectral Radiation Bandwidth | $\Delta \lambda$ | $I_{F}=20 \mathrm{~mA}$ | - | 30 | - | nm |

## INTERNAL CIRCUIT DIAGRAMS



## TYPICAL APPLICATION CIRCUITS



Internal Components are not customer accessible


## OPTICAL CHARACTERISTIC CURVES



Fig. 1 RELATIVE INTENSITY VS. FORWARD CURRENT


Fig. 3 RELATIVE INTENSITY VS.LEAD TEMPERATURE (PULSED 20 mA ; 300us
PULSE,10ms PERIOD)


Fig. 5 RELATIVE INTENSITY VS. WAVELENGTH


Fig. 2 FORWARD CURRENT VS. FORWARD VOLTAG


FORWARD VOLTAGE(V)
Fig. 4 PEAK FORWARD VOLTAGE VS.FORWARD(100us TEST PULSE, 1\% DUTY CYCLE)


AMBIENT TEMPERATURE (TA)- ${ }^{\circ} \mathrm{C}$
Fig. 6 MAX. ALLOWABLE DC CURRENT VS. AMBIENT TEMPERATIJRE

## SOLDERING CHARACTERISTICS



## NOTES

1. Recommend pre-heat temperature of $105^{\circ} \mathrm{C}$ or less (as measured with a thermocouple attached to the LED pins) prior to immersion in the solder wave with a maximum solder bath temperature of $260^{\circ} \mathrm{C}$
2. Peak wave soldering temperature between $245^{\circ} \mathrm{C} \sim 225^{\circ} \mathrm{C}$ for $3 \mathrm{sec}(5 \mathrm{sec}$ max)
3. No more than one wave soldering pass

## SOLDERING IRON

- Basic spec is $\leqq 4 \mathrm{sec}$ when $260^{\circ} \mathrm{C}$. If temperature is higher, time should be shorter $\left(+10^{\circ} \mathrm{C} \rightarrow 1 \mathrm{sec}\right)$. Power dissipation of Iron should be smaller than 15 W , and temperature should be controllable. Surface temperature of the device should be under $230^{\circ} \mathrm{C}$


## REWORK

1. Customer must finish rework within 3 sec under $350^{\circ} \mathrm{C}$
2. The head of soldering iron cannot touch copper foil
